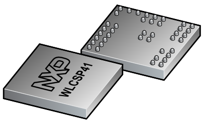

SOT1926-1

WLCSP41, wafer level chip-scale package; 41 bumps; 1.500 mm x 1.455 mm x 0.275 mm body

16 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP41
Package type industry code	WLCSP41
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	14-6-2017
Manufacturer package code	SOT1926

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	1.5	-	mm
E	package width		-	-	1.455	-	mm
A	seated height		-	-	-	-	mm
A_2	package height		-	-	0.275	-	mm
n_2	actual quantity of termination		-	-	41	-	

2. Package outline

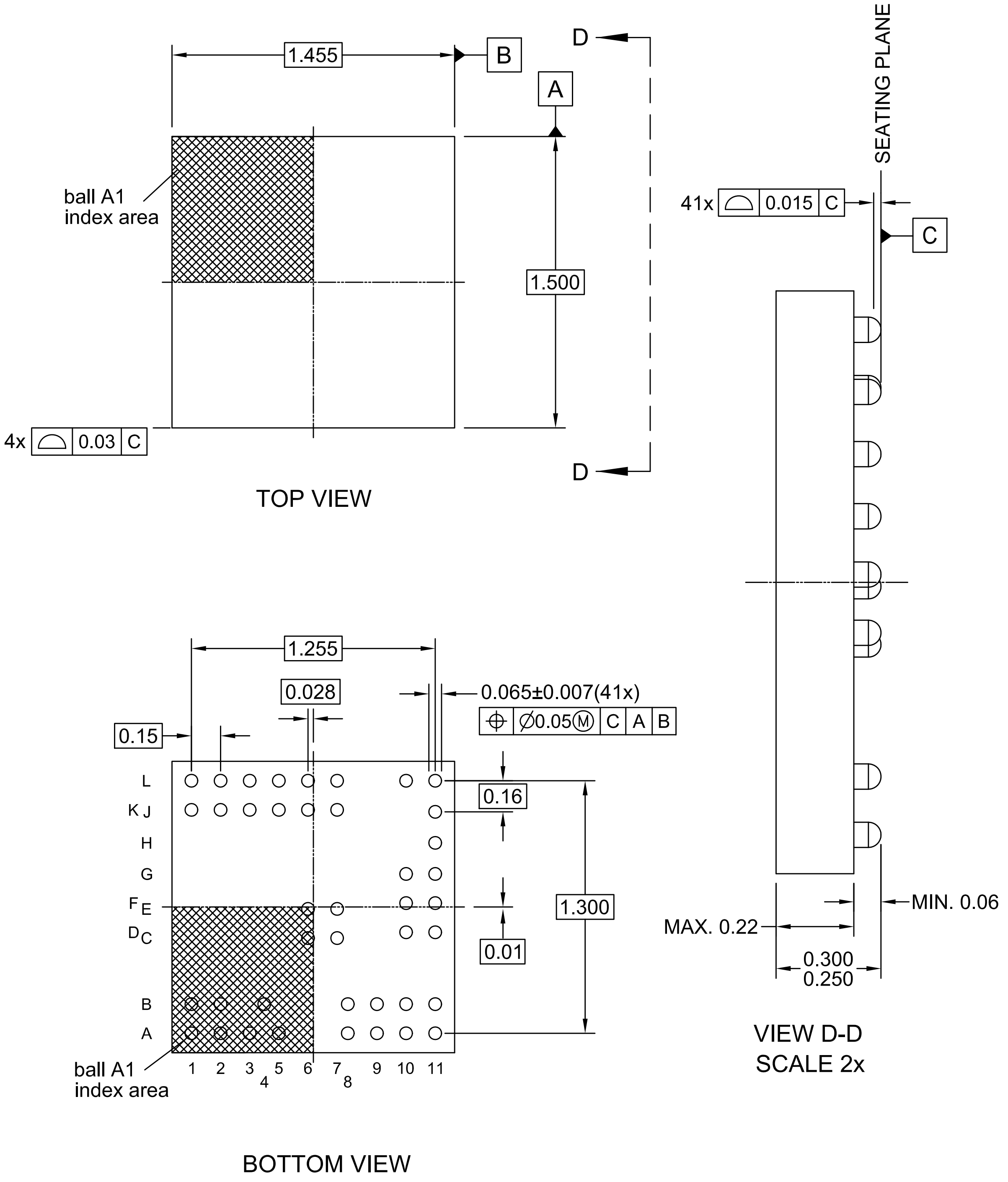

Fig. 1. Package outline WLCSP41 (SOT1926-1)

Bottom View (looking at the bumps)

LTE5201xC Bumps Coordination

Bump	X (um)	Y (um)
A1	-627.5	-650.0
B1	-627.5	-500.0
K1	-627.5	500.0
L1	-627.5	650.0
A2	-477.5	-650.0
B2	-477.5	-500.0
K2	-477.5	500.0
L2	-477.5	650.0
A3	-327.5	-650.0
K3	-327.5	500.0
L3	-327.5	650.0
B4	-252.5	-500.0
A5	-177.5	-650.0
K5	-177.5	500.0
L5	-177.5	650.0
C6	-27.5	-160.0
E6	-27.5	-10.0
K6	-27.5	500.0
L6	-27.5	650.0
C7	122.5	-160.0

Bump	X (um)	Y (um)
E7	122.5	-10.0
K7	122.5	500.0
L7	122.5	650.0
A8	177.5	-650.0
B8	177.5	-500.0
A9	327.5	-650.0
B9	327.5	-500.0
A10	477.5	-650.0
B10	477.5	-500.0
D10	477.5	-130.0
F10	477.5	20.0
G10	477.5	170.0
L10	477.5	650.0
A11	627.5	-650.0
B11	627.5	-500.0
D11	627.5	-130.0
F11	627.5	20.0
G11	627.5	170.0
H11	627.5	330.0
J11	627.5	490.0
L11	627.5	650.0

Notes: CoordInates w.r.t center of chip

Fig. 2. Package outline note WLCSP41 (SOT1926-1)

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4. Contents

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